

- CLASS II FABRICATION NOTES: (UNLESS OTHERWISE SPECIFIED)
1. BOARDS SHALL BE 100% NET LIST TESTED FOR OPENS AND SHORTS PER PROVIDED IPC-D-356 NETLIST.
 2. THIS BOARD SHALL BE MANUFACTURED IN ACCORDANCE WITH IPC-6012A CLASS II SPECIFICATIONS AND MEET IPC-600 CLASS II ACCEPTABILITY STANDARDS.
 3. MATERIAL:
 - a. FR4 PER IPC 4101B/24 /26, OR /28.
 - b. SIGNAL LAYERS TO BE 1 OZ. COPPER.
 - c. PLANE LAYERS TO BE 1 OZ. COPPER.
 - d. OVERALL THICKNESS TO BE 0.062" +/- 10%
 4. LEGEND:
 - a. WHITE NON-CONDUCTIVE EPOXY INK BOTH SIDES.

5. SOLDERMASK:
 - a. APPLY LIQUID PHOTO-IMAGABLE (LPI) SOLDER MASK OVER BARE COPPER PER IPC-SM-840 CLASS H, COLOR MATTE BLUE, BOTH SIDES.
6. PLATING FINISH:
 - a. HOT AIR SOLDER LEVELING (HASL) SN63A SnPb SOLDER.
 - ~~b. IMMERSION SILVER INK~~
7. PROCESS ALLOWANCES:
 - a. MAXIMUM BOW AND TWIST SHALL NOT EXCEED .007" PER INCH
 - b. HOLE DIMENSIONS APPLY AFTER PLATING.
 - c. ALL HOLES SHALL BE LOCATED WITHIN 0.003" DIAMETER OF TRUE POSITION.
 - d. LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.003".
 - e. CONDUCTOR WIDTHS AND SPACING SHALL BE WITHIN +/- 0.002".
 - f. REMOVE ALL BURRS AND BREAK SHARP EDGES 0/015" MAX.
 - g. CUT OUTSIDE OF 0.001" BOARD OUTLINE.

